

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



August 1997

FDV303N DigitalFET, N-Channel

General Description

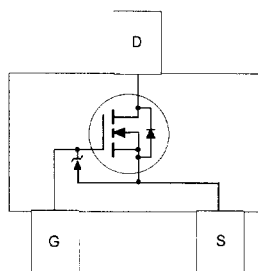
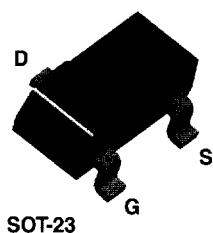
These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance at low gate drive conditions. This device is designed especially for application in battery circuits using either one lithium or three cadmium or NMH cells. It can be used as an inverter or for high-efficiency miniature discrete DC/DC conversion in compact portable electronic devices like cellular phones and pagers. This device has excellent on-state resistance even at gate drive voltages as low as 2.5 volts.

Features

- 25 V, 0.68 A continuous, 2 A Peak.
 $R_{DS(ON)} = 0.45 \Omega @ V_{GS} = 4.5 \text{ V}$
 $R_{DS(ON)} = 0.6 \Omega @ V_{GS} = 2.7 \text{ V}$
- Very low level gate drive requirements allowing direct operation in 3V circuits. $V_{GS(th)} < 1.5 \text{ V}$.
- Gate-Source Zener for ESD ruggedness.
>6kV Human Body Model
- Compact industry standard SOT-23 surface mount package.
- Alternative to TN0200T and TN0201T.



Mark:303



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless other wise noted

Symbol	Parameter	FDV303N	Units
V_{DSS}	Drain-Source Voltage, Power Supply Voltage	25	V
V_{GSS}	Gate-Source Voltage, V_{IN}	8	V
I_D	Drain/Output Current - Continuous	0.68	A
	- Pulsed	2	
P_D	Maximum Power Dissipation	0.35	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)	6.0	kV

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	$^\circ\text{C/W}$
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Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	25			V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	$I_D = 250\text{ }\mu\text{A}$ Referenced to $25\text{ }^\circ\text{C}$		26		mV / $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$ $T_J = 55^\circ\text{C}$			1	μA
					10	μA
I_{GSS}	Gate - Body Leakage Current	$V_{GS} = 8\text{ V}, V_{DS} = 0\text{ V}$			100	nA
ON CHARACTERISTICS (Note)						
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	$I_D = 250\text{ }\mu\text{A}$ Referenced to $25\text{ }^\circ\text{C}$		-2.6		mV / $^\circ\text{C}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	0.65	0.8	1.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5\text{ V}, I_D = 0.5\text{ A}$ $T_J = 125^\circ\text{C}$		0.33	0.45	Ω
				0.52	0.8	
		$V_{GS} = 2.7\text{ V}, I_D = 0.2\text{ A}$		0.44	0.6	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 2.7\text{ V}, V_{DS} = 5\text{ V}$	0.5			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 0.5\text{ A}$		1.45		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		50		pF
C_{oss}	Output Capacitance			28		pF
C_{rss}	Reverse Transfer Capacitance			9		pF
SWITCHING CHARACTERISTICS (Note)						
$t_{D(on)}$	Turn - On Delay Time	$V_{DD} = 6\text{ V}, I_D = 0.5\text{ A},$ $V_{GS} = 4.5\text{ V}, R_{GEN} = 50\text{ }\Omega$		3	6	ns
t_r	Turn - On Rise Time			8.5	18	ns
$t_{D(off)}$	Turn - Off Delay Time			17	30	ns
t_f	Turn - Off Fall Time			13	25	ns
Q_g	Total Gate Charge	$V_{DS} = 5\text{ V}, I_D = 0.5\text{ A},$ $V_{GS} = 4.5\text{ V}$		1.64	2.3	nC
Q_{gs}	Gate-Source Charge			0.38		nC
Q_{gd}	Gate-Drain Charge			0.45		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I_S	Maximum Continuous Drain-Source Diode Forward Current				0.3	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 0.5\text{ A}$ (Note)		0.83	1.2	V

Note:

Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

Typical Electrical Characteristics

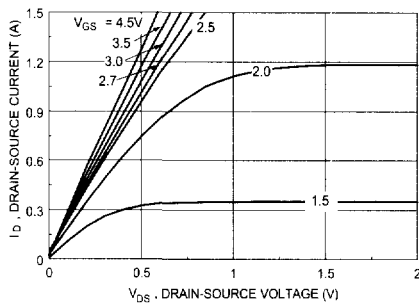


Figure 1. On-Region Characteristics.

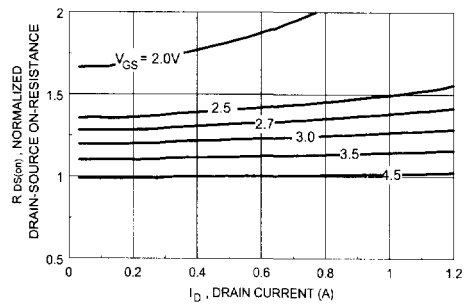


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

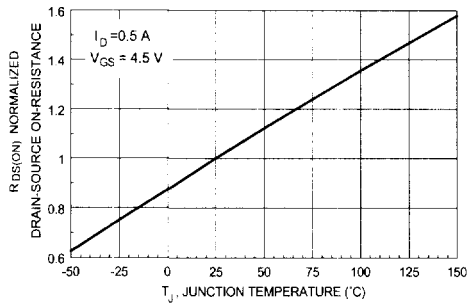


Figure 3. On-Resistance Variation with Temperature.

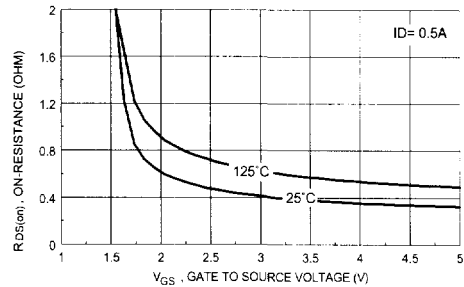


Figure 4. On-Resistance Variation with Gate-To-Source Voltage.

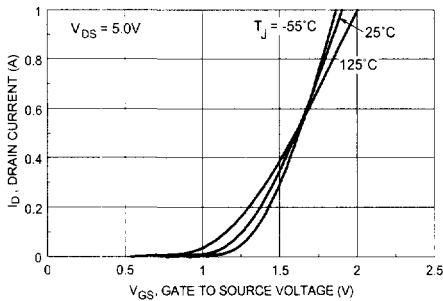


Figure 5. Transfer Characteristics.

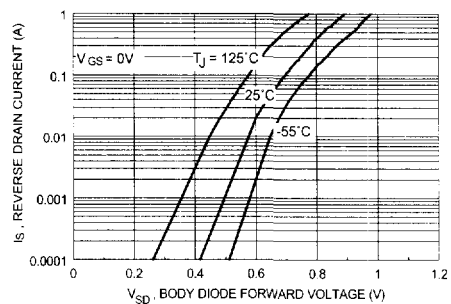


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical And Thermal Characteristics

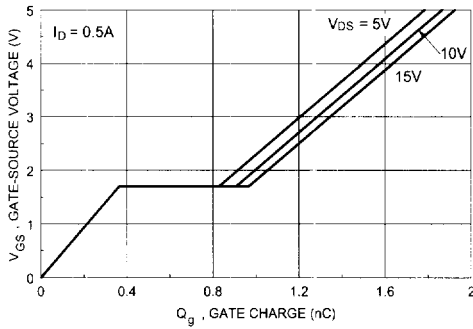


Figure 7. Gate Charge Characteristics.

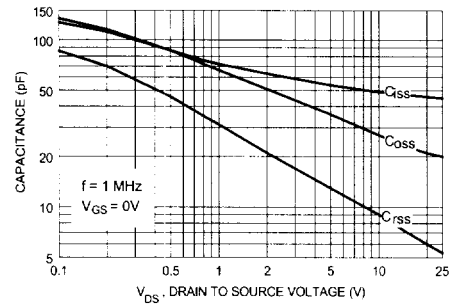


Figure 8. Capacitance Characteristics.

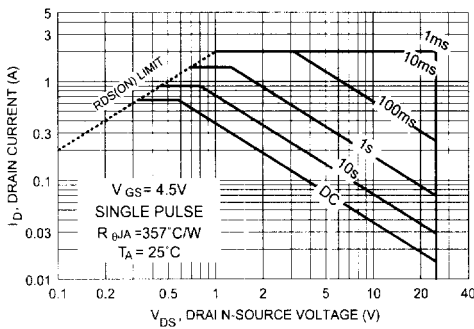


Figure 9. Maximum Safe Operating Area.

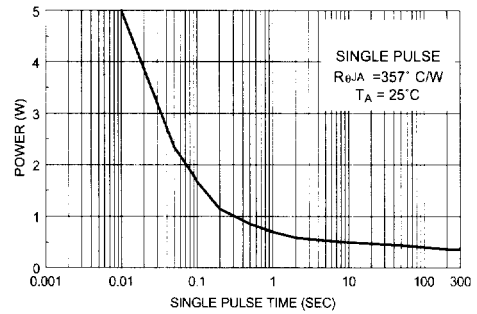


Figure 10. Single Pulse Maximum Power Dissipation.

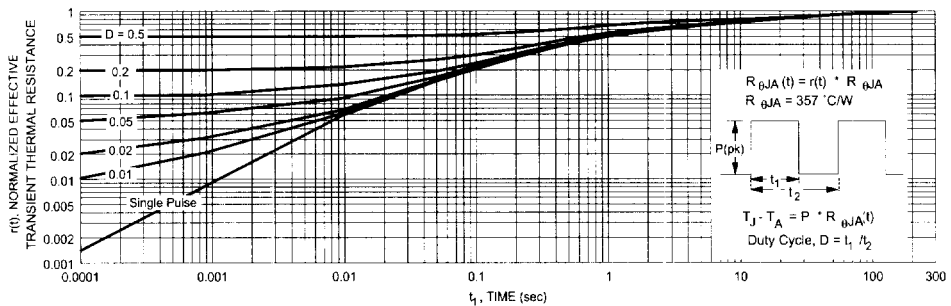


Figure 11. Transient Thermal Response Curve.